

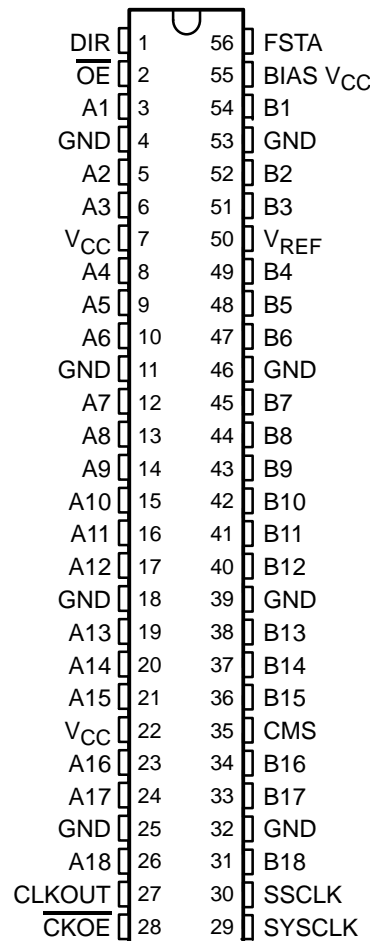
SN74GTLPH16927

18-BIT LVTTTL-TO-GTLP BUS TRANSCEIVER WITH SOURCE-SYNCHRONOUS CLOCK OUTPUTS

SCES413 – OCTOBER 2002

- Member of the Texas Instruments Widebus™ Family
- TI-OPC™ Circuitry Limits Ringing on Unevenly Loaded Backplanes
- OEC™ Circuitry Improves Signal Integrity and Reduces Electromagnetic Interference
- Bidirectional Interface Between GTLP Signal Levels and LVTTTL Logic Levels
- GTLP Buffered SYCLK Signal (SSCLK) for Source-Synchronous Applications
- LVTTTL Interfaces Are 5-V Tolerant
- Medium-Drive GTLP Outputs (50 mA)
- LVTTTL Outputs (–24 mA/24 mA)
- GTLP Rise and Fall Times Designed for Optimal Data-Transfer Rate and Signal Integrity in Distributed Loads
- I_{off} , Power-Up 3-State, and BIAS V_{CC} Support Live Insertion
- Bus Hold on A-Port Data Inputs
- Distributed V_{CC} and GND Pins Minimize High-Speed Switching Noise
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)

DGG OR DGV PACKAGE
(TOP VIEW)



description/ordering information

The SN74GTLPH16927 is a medium-drive, 18-bit bus transceiver that provides LVTTTL-to-GTLP and GTLP-to-LVTTTL signal-level translation. The device allows for transparent and latched modes of data transfer. Additionally, with the use of the clock-mode select (CMS) input, the device can be used in source-synchronous and clock-synchronous applications. Source-synchronous applications require the skew between the clock output and data output to be minimized for optimum maximum-frequency system performance. In order to reduce this skew, a flexible setup-time adjustment (FSTA) feature is incorporated into the device that sets a predetermined delay between the clock and data. The CMS and direction (DIR) inputs control the mode of the device.

ORDERING INFORMATION

T _A	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 85°C	TSSOP – DGG	Tape and reel	SN74GTLPH16927GR	GTLPH16927
	TVSOP – DGV	Tape and reel	SN74GTLPH16927VR	GL927
	VFBGA – GQL	Tape and reel	SN74GTLPH16927KR	GL927

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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description/ordering information (continued)

The system clock (SYSCLK) and CLKOUT pins are LVTTTL compatible, while the source-synchronous I/O is GTLP compatible. The benefits include compensation for output-to-output skew coming from the driver itself, and compensation for process skew if more than one driver is used. The device provides a high-speed interface between cards operating at LVTTTL logic levels and a backplane operating at GTLP signal levels. High-speed (about three times faster than standard TTL or LVTTTL) backplane operation is a direct result of GTLP's reduced output swing (<1 V), reduced input threshold levels, improved differential input, OEC™ circuitry, and TI-OPC™ circuitry. Improved GTLP OEC and TI-OPC circuits minimize bus-settling time and have been designed and tested using several backplane models. The medium drive allows incident-wave switching in heavily loaded backplanes with equivalent load impedance down to 11Ω .

GTLP is the Texas Instruments derivative of the Gunning Transceiver Logic (GTL) JEDEC standard JESD 8-3. The ac specification of the SN74GTLP16927 is given only at the preferred higher noise-margin GTLP, but the user has the flexibility of using this device at either GTL ($V_{TT} = 1.2$ V and $V_{REF} = 0.8$ V) or GTLP ($V_{TT} = 1.5$ V and $V_{REF} = 1$ V) signal levels. For information on using GTLP devices in FB+/BTL applications, refer to TI application reports, *Texas Instruments GTLP Frequently Asked Questions*, literature number SCEA019, and *GTLP in BTL Applications*, literature number SCEA017.

Normally, the B port operates at GTLP signal levels. The A-port and control inputs operate at LVTTTL logic levels, but are 5-V tolerant and are compatible with TTL and 5-V CMOS inputs. V_{REF} is the B-port differential input reference voltage.

This device is fully specified for live-insertion applications using I_{off} , power-up 3-state, and BIAS V_{CC} . The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down. The power-up 3-state circuitry places the outputs in the high-impedance state during power up and power down, which prevents driver conflict. The BIAS V_{CC} circuitry precharges and preconditions the B-port input/output connections, preventing disturbance of active data on the backplane during card insertion or removal, and permits true live-insertion capability.

This GTLP device features TI-OPC circuitry, which actively limits the overshoot caused by improperly terminated backplanes, unevenly distributed cards, or empty slots during low-to-high signal transitions. This improves signal integrity, which allows adequate noise margin to be maintained at higher frequencies.

Active bus-hold circuitry holds unused or undriven LVTTTL data inputs at a valid logic state. Use of pullup or pulldown resistors with the bus-hold circuitry is not recommended.

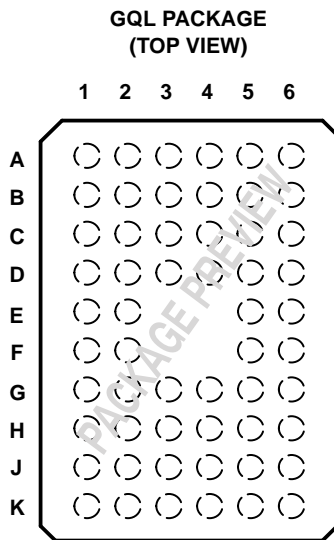
When V_{CC} is between 0 and 1.5 V, the device is in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 1.5 V, the output-enable (\overline{OE}) input should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.



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terminal assignments

	1	2	3	4	5	6
A	A1	\overline{OE}	DIR	FSTA	BIAS V_{CC}	B1
B	A3	A2	GND	GND	B2	B3
C	A5	A4	V_{CC}	V_{REF}	B4	B5
D	A7	A6	GND	GND	B6	B7
E	A9	A8			B8	B9
F	A10	A11			B11	B10
G	A12	A13	GND	GND	B13	B12
H	A14	A15	V_{CC}	CMS	B15	B14
J	A16	A17	GND	GND	B17	B16
K	A18	CLKOUT	\overline{CKOE}	SYSCLK	SSCLK	B18

functional description

The SN74GTLPH16927 is a medium-drive (50 mA), 18-bit bus transceiver containing D-type latches and D-type flip-flops for data-path operation in transparent or latched modes and can replace any of the functions shown in Table 1. Data polarity is noninverting.

Table 1. SN74GTLPH16927 Bus-Transceiver Replacement Functions

FUNCTION	8 BIT	9 BIT	10 BIT	16 BIT	18 BIT
Transceiver	'245, '623, '645	'863	'861	'16245, '16623	'16863
Buffer/driver	'241, '244, '541		'827	'16241, '16244, '16541	'16825
Latched transceiver	'543			'16543	'16472
Latch	'373, '573	'843	'841	'16373	'16843
SN74GTLPH16927 bus transceiver replaces all above functions					

Additionally, the device allows for conversion of the system clock (SYSCLK) to GTLP signal levels (SSCLK) and LVTTTL signal levels (CLKOUT). It also provides conversion of a GTLP source-synchronous clock to LVTTTL signal levels (CLKOUT).

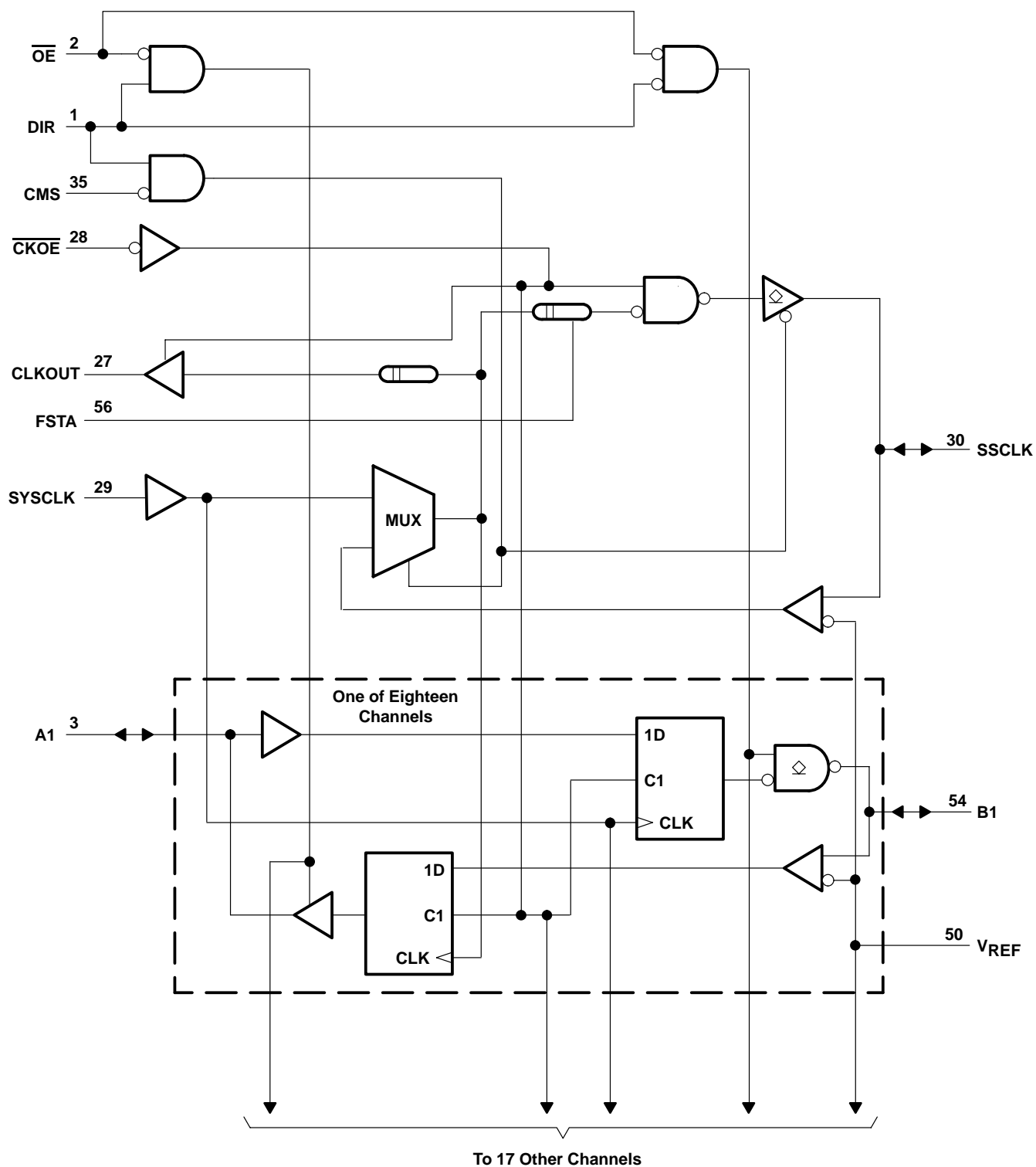
The device allows for conversion of the LVTTTL system clock (SYSCLK) to GTLP (SSCLK) and LVTTTL (CLKOUT) signal levels when used as the transmitter and GTLP source-synchronous clock (SSCLK) to LVTTTL (CLKOUT) signal levels when used as the receiver in source-synchronous applications. Source-synchronous operation removes time-of-flight restrictions and allows for increased data throughput. CMS is used to switch between system-synchronous mode and clock-synchronous mode. The clock output-enable (\overline{CKOE}) input is used to switch between latched and transparent mode.

Data flow in each direction is controlled by \overline{CKOE} , clock (SYSCLK or SSCLK), DIR, and \overline{OE} . \overline{OE} controls the 18 bits of data. The CLKOUT/SSCLK buffered clock path for the A-to-B and B-to-A directions is controlled by \overline{CKOE} . In the data-isolation mode (\overline{OE} high, \overline{CKOE} low), A data can be stored in one register and/or B data can be stored in the other register.

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logic diagram (positive logic)



Pin numbers shown are for the DGG and DGV packages.



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Function Tables

A-TO-B DIRECTION

INPUTS						OUTPUTS			MODE	
\overline{CKOE}	\overline{OE}	CMS	DIR	SYSCLK	A	SSCLK	CLKOUT	B		
L	L	X	L	H or L	X	SYSCLK	SYSCLK	B ₁	Latched storage of A	Source synchronous
L	L	X	L	↑	L	SYSCLK	SYSCLK	L	Clocked storage of A	
L	L	X	L	↑	H	SYSCLK	SYSCLK	H		
L	H	X	L	X	X	SYSCLK	SYSCLK	Z	Data isolation	
H	L	X	L	X	L	Z	Z	L	Transparent transmission of A	
H	L	X	L	X	H	Z	Z	H		
H	H	X	X	X	X	Z	Z	Z	Isolation	
L	H	H	X	↑	X	SYSCLK	SYSCLK	Z	Transmit SYSCLK	
L	H	H	X	H or L	X	SYSCLK	SYSCLK	Z		

B-TO-A DIRECTION

INPUTS							OUTPUTS			MODE	
\overline{CKOE}	\overline{OE}	CMS	DIR	SYSCLK	SSCLK	B	SSCLK	CLKOUT	A		
L	L	L	H	X	H or L	X	Input	SSCLK	A ₁	Latched storage of B	Source synchronous
L	L	L	H	X	↑	L	Input	SSCLK	L	Clocked storage of B	
L	L	L	H	X	↑	H	Input	SSCLK	H		
L	H	L	H	X	X	X	Input	SSCLK	Z	Data isolation	
L	L	H	H	H or L	Output	X	SYSCLK	SYSCLK	A ₁	Latched storage of B	Clock synchronous
L	L	H	H	↑	Output	L	SYSCLK	SYSCLK	L	Clocked storage of B	
L	L	H	H	↑	Output	H	SYSCLK	SYSCLK	H		
L	H	H	H	X	Output	X	SYSCLK	SYSCLK	Z	Data isolation	
H	L	X	H	X	Output	L	Z	Z	L	Transparent transmission of B	
H	L	X	H	X	Output	H	Z	Z	H		
H	H	X	X	X	Output	X	Z	Z	Z	Isolation	
L	H	L	X	X	↑	X	Input	SSCLK	Z	Receive SSCLK	
L	H	L	X	X	H or L	X	Input	SSCLK	Z		

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recommended operating conditions (see Notes 4 through 7)

		MIN	NOM	MAX	UNIT		
V_{CC} , BIAS V_{CC}	Supply voltage	3.15	3.3	3.45	V		
V_{TT}	Termination voltage	GTL	1.14	1.2	1.26	V	
		GTLP	1.35	1.5	1.65		
V_{REF}	Reference voltage	GTL	0.74	0.8	0.87	V	
		GTLP	0.87	1	1.1		
V_I	Input voltage	B port and SSCLK	V_{TT}		V		
		Except B port and SSCLK	V_{CC} 5.5				
V_{IH}	High-level input voltage	B port and SSCLK	$V_{REF}+0.05$		V		
		Except B port, FSTA, and SSCLK	2				
V_{IL}	Low-level input voltage	B port and SSCLK	$V_{REF}-0.05$		V		
		Except B port, FSTA, and SSCLK	0.8				
I_{IK}	Input clamp current				-18	mA	
I_{OH}	High-level output current	A port and CLKOUT				-24	mA
I_{OL}	Low-level output current	A port and CLKOUT				24	mA
		B port and SSCLK				50	
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled			10	ns/V	
$\Delta t/\Delta V_{CC}$	Power-up ramp rate	20				μ s/V	
T_A	Operating free-air temperature	-40			85	$^{\circ}$ C	

- NOTES: 4. All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.
5. Proper connection sequence for use of the B-port I/O precharge feature is GND and BIAS $V_{CC} = 3.3$ V first, I/O second, and $V_{CC} = 3.3$ V last, because the BIAS V_{CC} precharge circuitry is disabled when any V_{CC} pin is connected. The control and V_{REF} inputs can be connected anytime, but normally are connected during the I/O stage. If B-port precharge is not required, any connection sequence is acceptable but, generally, GND is connected first.
6. V_{TT} and R_{TT} can be adjusted to accommodate backplane impedances if the dc recommended I_{OL} ratings are not exceeded.
7. V_{REF} can be adjusted to optimize noise margins, but normally is two-thirds V_{TT} . TI-OPC circuitry is enabled in the A-to-B direction and is activated when $V_{TT} > 0.7$ V above V_{REF} . If operated in the A-to-B direction, V_{REF} should be set to within 0.6 V of V_{TT} to minimize current drain.

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electrical characteristics over recommended operating free-air temperature range for GTLP (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP†	MAX	UNIT
V _{IK}		V _{CC} = 3.15 V, I _I = -18 mA				-1.2	V
V _{OH}	A port and CLKOUT	V _{CC} = 3.15 V to 3.45 V, I _{OH} = -100 μA		V _{CC} -0.2			V
		V _{CC} = 3.15 V, I _{OH} = -12 mA		2.4			
		V _{CC} = 3.15 V, I _{OH} = -24 mA		2			
V _{OL}	A port and CLKOUT	V _{CC} = 3.15 V to 3.45 V, I _{OL} = 100 μA				0.2	V
		V _{CC} = 3.15 V, I _{OL} = 12 mA				0.4	
		V _{CC} = 3.15 V, I _{OL} = 24 mA				0.5	
	B port and SSCLK	V _{CC} = 3.15 V to 3.45 V, I _{OL} = 100 μA				0.2	
		V _{CC} = 3.15 V, I _{OL} = 10 mA				0.2	
		V _{CC} = 3.15 V, I _{OL} = 40 mA				0.4	
		V _{CC} = 3.15 V, I _{OL} = 50 mA				0.55	
I _I	SYSCLOCK and control inputs	V _{CC} = 3.45 V, V _I = 0 to 5.5 V				±10	μA
I _{OZ} ‡	B port and SSCLK	V _{CC} = 3.45 V, V _{REF} within 0.6 V of V _{TT} , V _O = 0 to 2.3 V				±10	μA
	CLKOUT	V _{CC} = 3.45 V, V _O = 0 to 5.5 V				±10	
I _{OZH} ‡	A port	V _{CC} = 3.45 V, V _O = V _{CC}				10	μA
I _{OZL} ‡	A port	V _{CC} = 3.45 V, V _O = GND				-10	μA
I _{BHL} §	A port	V _{CC} = 3.15 V, V _I = 0.8 V		75			μA
I _{BHH} ¶	A port	V _{CC} = 3.15 V, V _I = 2 V		-75			μA
I _{BHLO} #	A port	V _{CC} = 3.45 V, V _I = 0 to V _{CC}		500			μA
I _{BHHO}	A port	V _{CC} = 3.45 V, V _I = 0 to V _{CC}		-500			μA
I _{CC}	A port, B port, or SSCLK	V _{CC} = 3.45 V, I _O = 0, V _I (A-port or control input) = V _{CC} or GND, V _I (B port) = V _{TT} or GND		Outputs high		50	mA
				Outputs low		50	
				Outputs disabled		50	
ΔI _{CC} *		V _{CC} = 3.45 V, One A-port or control input at V _{CC} - 0.6 V, Other A-port or control inputs at V _{CC} or GND				1.5	mA
C _i	SYSCLOCK inputs	V _I = 3.15 V or 0			3.5	5	pF
	Control inputs	V _I = 3.15 V or 0			3.5	5.5	
C _{io}	A port	V _O = 3.15 V or 0			7.5	10	pF
	B port or SSCLK	V _O = 1.5 V or 0			9	11	
C _o	CLKOUT	V _O = 3.15 V or 0			6	7.5	pF

† All typical values are at V_{CC} = 3.3 V, T_A = 25°C.

‡ For I/O ports, the parameter I_I includes the off-state output leakage current.

§ The bus-hold circuit can sink at least the minimum low sustaining current at V_{IL}max. I_{BHL} should be measured after lowering V_{IN} to GND and then raising it to V_{IL}max.

¶ The bus-hold circuit can source at least the minimum high sustaining current at V_{IH}min. I_{BHH} should be measured after raising V_{IN} to V_{CC} and then lowering it to V_{IH}min.

An external driver must source at least I_{BHLO} to switch this node from low to high.

|| An external driver must sink at least I_{BHHO} to switch this node from high to low.

* This is the increase in supply current for each input that is at the specified TTL voltage level, rather than V_{CC} or GND.



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hot-insertion specifications for A port over recommended operating free-air temperature range

PARAMETER	TEST CONDITIONS			MIN	MAX	UNIT
I_{off}	$V_{CC} = 0,$	BIAS $V_{CC} = 0,$	V_I or $V_O = 0$ to 5.5 V		10	μA
I_{OZPU}	$V_{CC} = 0$ to 1.5 V,	$V_O = 0.5$ V to 3 V,	$\overline{OE} = 0$		± 30	μA
I_{OZPD}	$V_{CC} = 1.5$ V to 0,	$V_O = 0.5$ V to 3 V,	$\overline{OE} = 0$		± 30	μA

live-insertion specifications for B port over recommended operating free-air temperature range

PARAMETER	TEST CONDITIONS			MIN	MAX	UNIT
I_{off}	$V_{CC} = 0,$	BIAS $V_{CC} = 0,$	V_I or $V_O = 0$ to 1.5 V		10	μA
I_{OZPU}	$V_{CC} = 0$ to 1.5 V,	BIAS $V_{CC} = 0,$	$V_O = 0.5$ V to 1.5 V, $\overline{OE} = 0$		± 30	μA
I_{OZPD}	$V_{CC} = 1.5$ V to 0,	BIAS $V_{CC} = 0,$	$V_O = 0.5$ V to 1.5 V, $\overline{OE} = 0$		± 30	μA
I_{CC} (BIAS V_{CC})	$V_{CC} = 0$ to 3.15 V	BIAS $V_{CC} = 3.15$ V to 3.45 V,	V_O (B port) = 0 to 1.5 V		5	mA
	$V_{CC} = 3.15$ V to 3.45 V				10	μA
V_O	$V_{CC} = 0,$	BIAS $V_{CC} = 3.3$ V,	$I_O = 0$	0.95	1.05	V
I_O	$V_{CC} = 0,$	BIAS $V_{CC} = 3.15$ V to 3.45 V,	V_O (B port) = 0.6 V	-1		μA

timing requirements over recommended ranges of supply voltage and operating free-air temperature, $V_{TT} = 1.5$ V and $V_{REF} = 1$ V for GTLP (unless otherwise noted)

			MIN	MAX	UNIT
f_{clock}	Clock frequency			175	MHz
t_w	Pulse duration	\overline{CKOE} high	2.8		ns
		SYSCLK or SSCLK high or low	3.3		
t_{su}	Setup time	A before SYSCLK \uparrow	1.2		ns
		B before SYSCLK \uparrow or SSCLK \uparrow	2.6		
		A before \overline{CKOE} \downarrow	1.2		
		B before \overline{CKOE} \downarrow	2.6		
t_h	Hold time	A after SYSCLK \uparrow	0.3		ns
		B after SYSCLK \uparrow or SSCLK \uparrow	0.8		
		A after \overline{CKOE} \downarrow	1.1		
		B after \overline{CKOE} \downarrow	0.3		

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switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $V_{TT} = 1.5\text{ V}$ and $V_{REF} = 1\text{ V}$ for GTLP (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	MIN	TYP†	MAX	UNIT
f_{max}	A	B	175			MHz
t_{PLH}	A	B	3.1		6.5	ns
t_{PHL}			3.1		6.5	
t_{PLH}	\overline{CKOE}	B	3.6		7.1	ns
t_{PHL}			3.6		7.1	
t_{PLH}	SYSCLK	B	3.7		7.3	ns
t_{PHL}			3.7		7.3	
t_{en}	\overline{OE}	B	3.3		7	ns
t_{dis}			3.3		7	
t_r	Rise time, B and SSCLK outputs (20% to 80%)		2.2			ns
t_f	Fall time, B and SSCLK outputs (80% to 20%)		1.5			ns
t_{PLH}	B	A	2		5.3	ns
t_{PHL}			2		5.3	
t_{PLH}	\overline{CKOE}	A	2.5		5.9	ns
t_{PHL}			2.5		5.9	
t_{PLH}	SYSCLK	A	2.4		5.9	ns
t_{PHL}			2.4		5.9	
t_{PLH}	SSCLK	A	2.9		6.7	ns
t_{PHL}			2.9		6.7	
t_{PLH}	SYSCLK	CLKOUT	3.6		7.5	ns
t_{PHL}			3.6		7.5	
t_{PLH}	SSCLK	CLKOUT	4		8.5	ns
t_{PHL}			4		8.5	
t_{en}	\overline{OE}	A	2.1		5.8	ns
t_{dis}			2.6		6.9	
t_{en}	\overline{CKOE}	CLKOUT	2.2		5.9	ns
t_{dis}			1.8		6	

† All typical values are at $V_{CC} = 3.3\text{ V}$, $T_A = 25^\circ\text{C}$



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skew characteristics over recommended ranges of supply voltage and operating free-air temperature, $V_{REF} = 1\text{ V}$ (unless otherwise noted); standard lumped loads, $C_L = 30\text{ pF}$ for B port (see Figure 1)[†]

PARAMETER	FROM (INPUT)	TO (OUTPUT)	FSTA	TEST CONDITIONS	MIN	MAX	UNIT
$t_{sk(LH)}^{\ddagger}$	SYSCLK	B			0.5		ns
$t_{sk(HL)}^{\ddagger}$					0.5		
$t_{sk(LH)}^{\ddagger}$	SYSCLK	SSCLK → B _n (see Figure 2)	GND	V _{CC} = 3.15 V, T = 85°C	3.4	4.7	ns
				V _{CC} = 3.3 V, T = 25°C	3.2	4.5	
				V _{CC} = 3.45 V, T = -40°C	3.1	4.4	
$t_{sk(HL)}^{\ddagger}$	SYSCLK	SSCLK → B _n (see Figure 2)	GND	V _{CC} = 3.15 V, T = 85°C	3.2	4.6	ns
				V _{CC} = 3.3 V, T = 25°C	2.8	4.1	
				V _{CC} = 3.45 V, T = -40°C	2.4	3.7	
$t_{sk(LH)}^{\ddagger}$	SYSCLK	SSCLK → B _n (see Figure 2)	V _{CC}	V _{CC} = 3.15 V, T = 85°C	7.1	8.9	ns
				V _{CC} = 3.3 V, T = 25°C	6.6	8.4	
				V _{CC} = 3.45 V, T = -40°C	6.3	8	
$t_{sk(HL)}^{\ddagger}$	SYSCLK	SSCLK → B _n (see Figure 2)	V _{CC}	V _{CC} = 3.15 V, T = 85°C	7.2	9	ns
				V _{CC} = 3.3 V, T = 25°C	6.5	8.2	
				V _{CC} = 3.45 V, T = -40°C	6	7.6	
$t_{sk(t)}^{\ddagger}$	SYSCLK	B			1.3		ns
$t_{sk(prLH)}^{\S}$	SYSCLK	B			1.8		ns
$t_{sk(prHL)}^{\S}$					2.8		

[†] Actual skew values between the GTLP outputs could vary on the backplane due to the loading and impedance seen by the device.

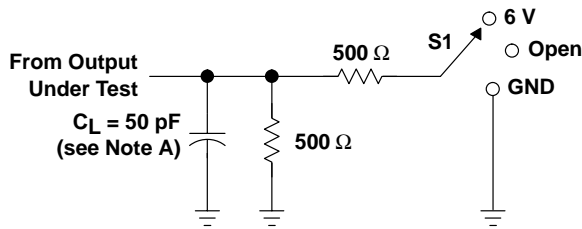
[‡] $t_{sk(LH)}/t_{sk(HL)}$ and $t_{sk(t)}$ – Output-to-output skew is defined as the absolute value of the difference between the actual propagation delay for all outputs with the same packaged device. The specifications are given for specific worst-case V_{CC} and temperature. The specifications apply to any outputs switching in the same direction, either high to low [$t_{sk(HL)}$], low to high [$t_{sk(LH)}$], or in opposite directions, both low to high and high to low [$t_{sk(t)}$].

[§] $t_{sk(prLH)}$ or $t_{sk(prHL)}$ – Part-to-part skew is designed as the absolute value of the difference between the actual propagation delay for all outputs from device to device. The parameter is specified for a specific worst-case V_{CC} and temperature. Furthermore, these values are provided by TI SPICE simulations.

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18-BIT LVTTTL-TO-GTLP BUS TRANSCEIVER
WITH SOURCE-SYNCHRONOUS CLOCK OUTPUTS

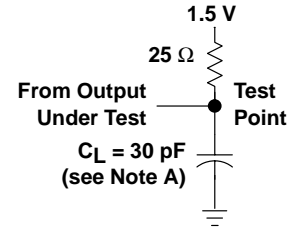
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PARAMETER MEASUREMENT INFORMATION

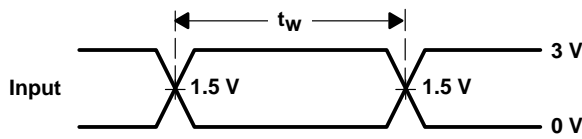


LOAD CIRCUIT FOR A OUTPUTS

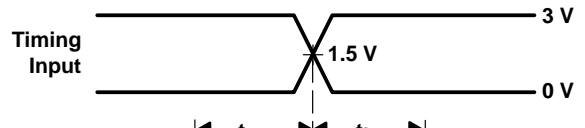
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	6 V
t_{PHZ}/t_{PZH}	GND



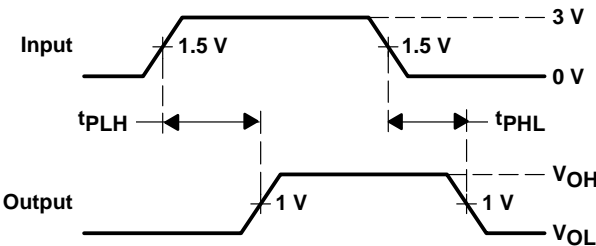
LOAD CIRCUIT FOR B OUTPUTS



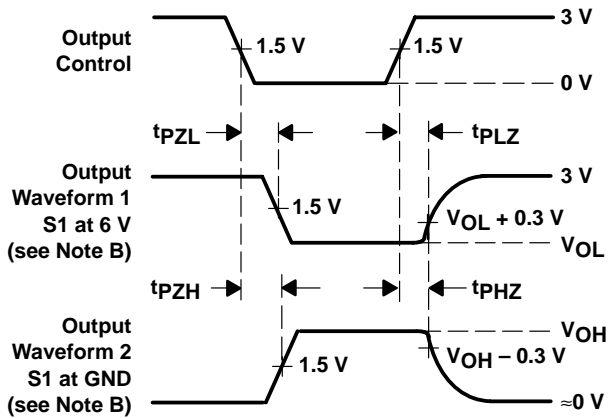
VOLTAGE WAVEFORMS PULSE DURATION



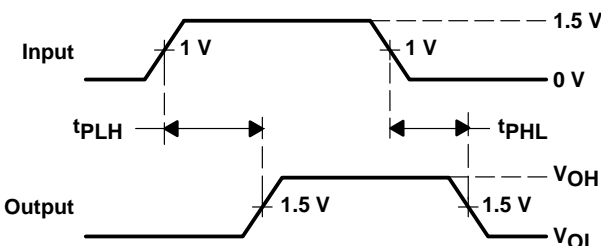
VOLTAGE WAVEFORMS SETUP AND HOLD TIMES
 $(V_M = 1.5\text{ V for A port and } 1\text{ V for B port})$
 $(V_{OH} = 3\text{ V for A port and } 1.5\text{ V for B port})$



VOLTAGE WAVEFORMS PROPAGATION DELAY TIMES (A port to B port)



VOLTAGE WAVEFORMS ENABLE AND DISABLE TIMES (A port)



VOLTAGE WAVEFORMS PROPAGATION DELAY TIMES (B port to A port)

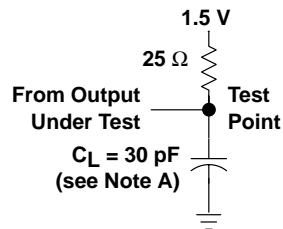
- NOTES: A. C_L includes probe and jig capacitance.
 B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10\text{ MHz}$, $Z_O = 50\ \Omega$, $t_r \leq 2\text{ ns}$, $t_f \leq 2\text{ ns}$.
 D. The outputs are measured one at a time with one transition per measurement.
 E. Load circuit for A outputs is also used for CLKOUT; load circuit for B outputs is also used for SSCLK.

Figure 1. Load Circuits and Voltage Waveforms

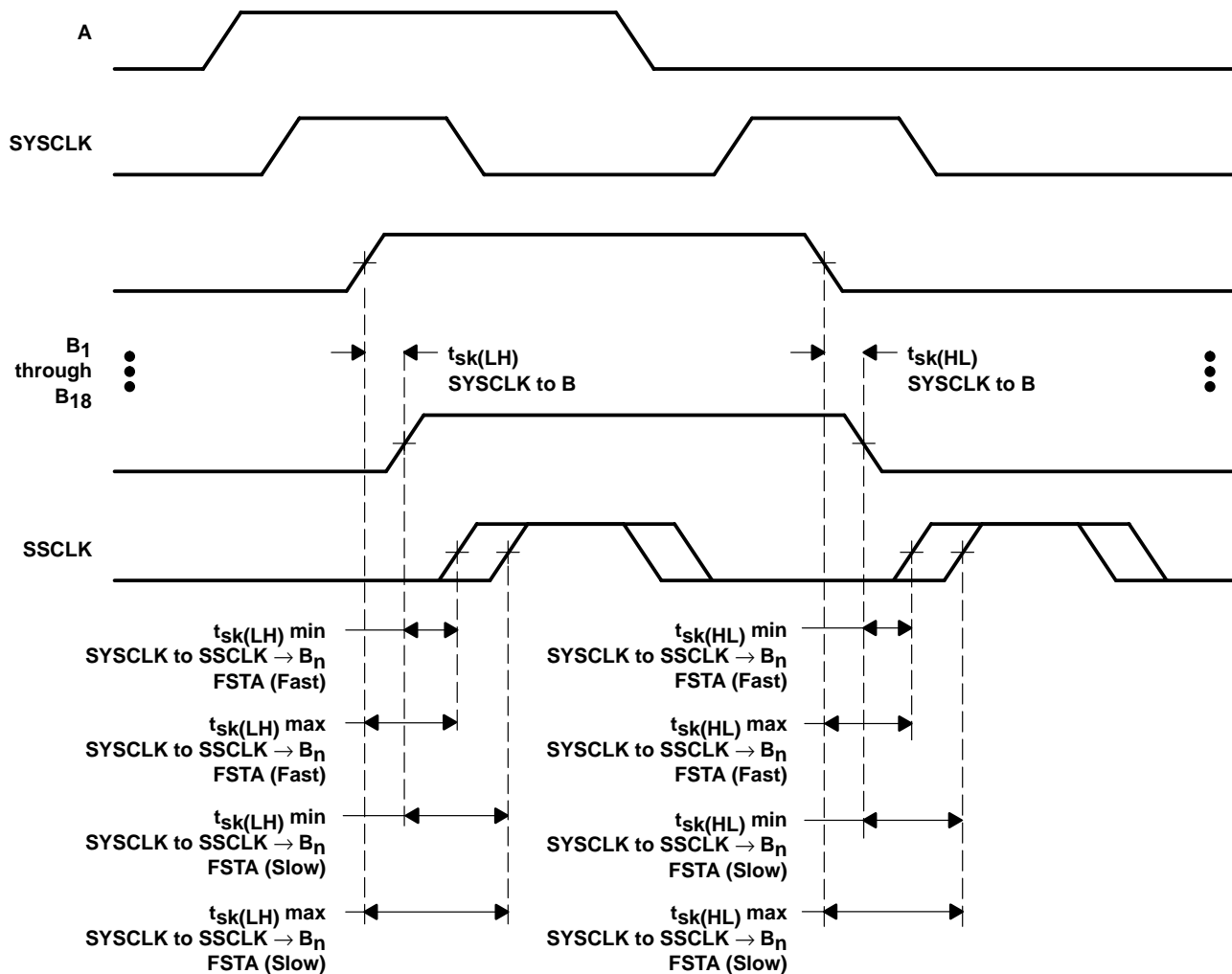


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LOAD CIRCUIT FOR B OUTPUTS



- NOTES: A. C_L includes probe and jig capacitance.
 B. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10$ MHz, $Z_O = 50 \Omega$, $t_r \leq 2$ ns, $t_f \leq 2$ ns.
 C. The outputs are measured one at a time with one transition per measurement.
 D. Load circuit for B outputs also is used for SSCLK.

Figure 2. Load Circuit and SYSCLK to SSCLK \rightarrow B_n Skew Waveforms

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DISTRIBUTED-LOAD BACKPLANE SWITCHING CHARACTERISTICS

The preceding switching characteristics table shows the switching characteristics of the device into a lumped load (Figure 1). However, the designer's backplane application probably is a distributed load. The physical representation is shown in Figure 3. This backplane, or distributed load, can be closely approximated to a resistor inductance capacitance (RLC) circuit, as shown in Figure 4. This device has been designed for optimum performance in this RLC circuit. The following switching characteristics table shows the switching characteristics of the device into the RLC load, to help the designer to better understand the performance of the GTLP device in this typical backplane. See www.ti.com/sc/gtlp for more information.

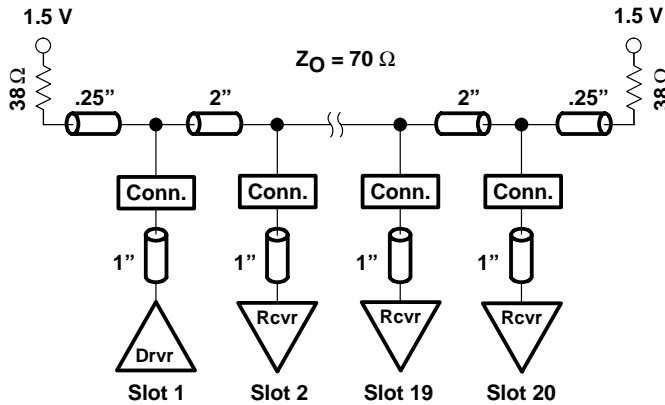


Figure 3. Medium-Drive Test Backplane

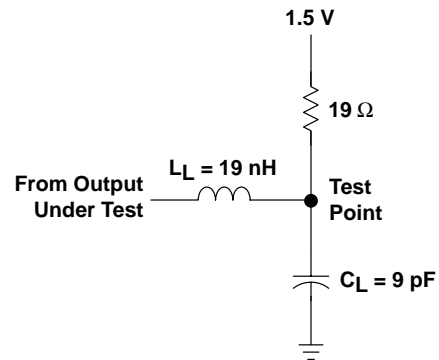


Figure 4. Medium-Drive RLC Network

switching characteristics over recommended operating conditions for the bus transceiver function (unless otherwise noted) (see Figure 4)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TYP†	UNIT
t _{PLH}	A	B	4.3	ns
t _{PHL}			4.3	
t _{PLH}	SYSCLK	B	5	ns
t _{PHL}			5	
t _r	Rise time, B and SSCLK outputs (20% to 80%)		1.2	ns
t _f	Fall time, B and SSCLK outputs (80% to 20%)		1.8	ns

† All typical values are at V_{CC} = 3.3 V, T_A = 25°C. All values are derived from TI SPICE models.

DGV (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

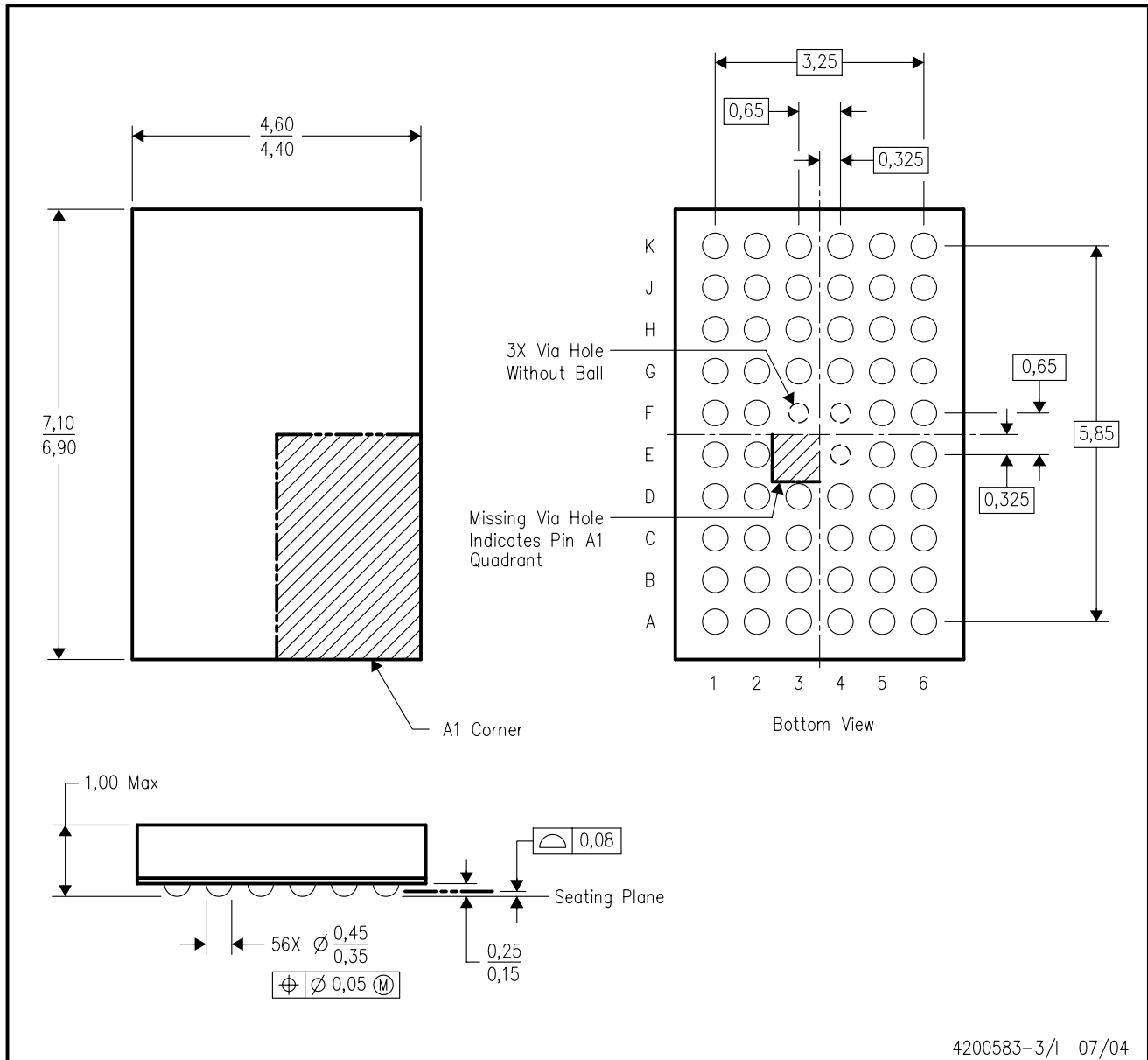
24 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.
 D. Falls within JEDEC: 24/48 Pins – MO-153
 14/16/20/56 Pins – MO-194

GQL (R-PBGA-N56)

PLASTIC BALL GRID ARRAY



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Falls within JEDEC MO-225 variation BA.
 - D. This package is tin-lead (SnPb). Refer to the 56 ZQL package (drawing 4204437) for lead-free.

DGG (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-153

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